BRIOCEAN

September 2025

Monthly Market Updates

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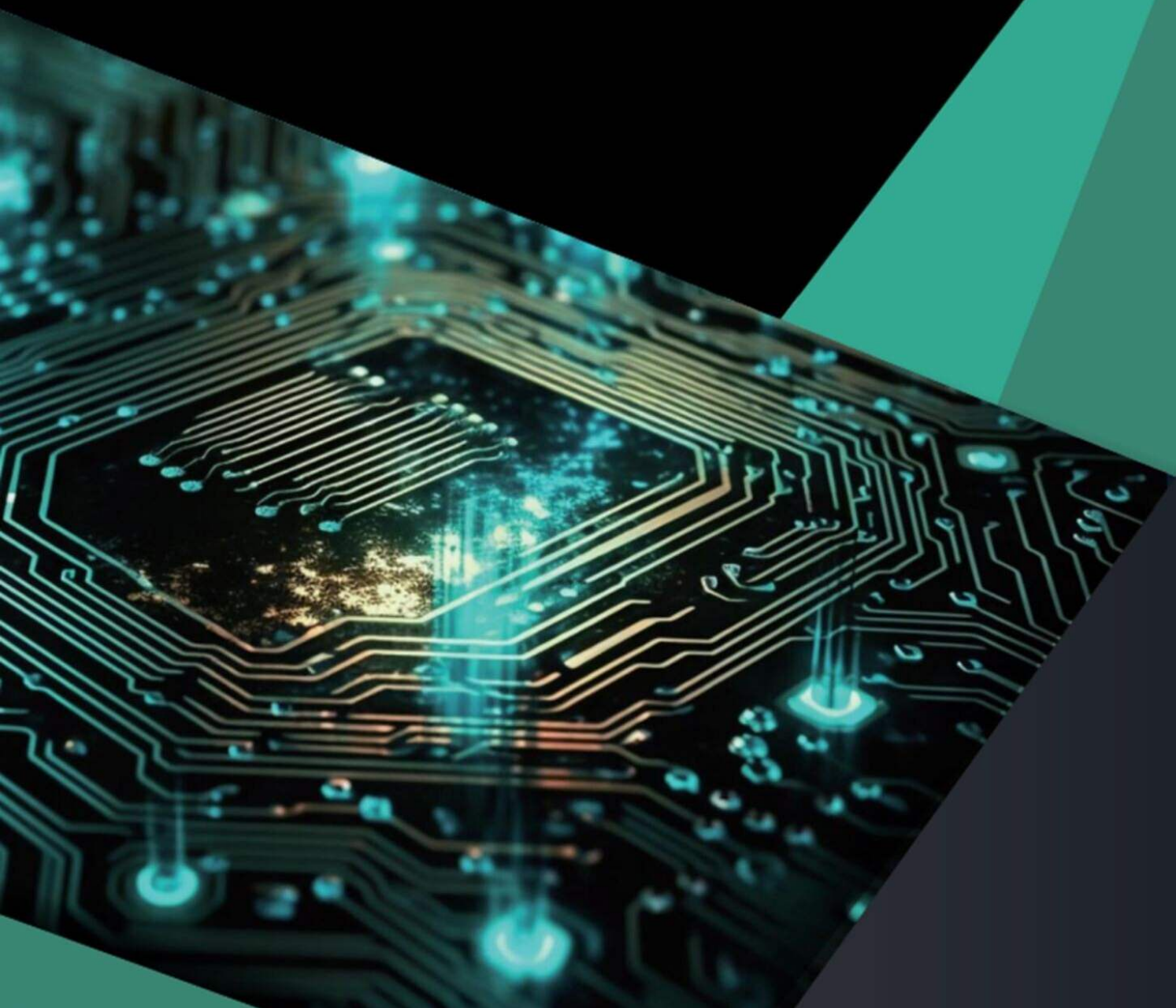

About Briocean

Briocean was established in 2008 as ISO9001:2005, and ANSI/ESD S20.20-2021 certified leading independent electronic component distributor, with our headquarters in Singapore. Our company specialises in sourcing and supply chain management services for the electronic manufacturing clients across a broad range of industries.

Our global network of over 10,000 vetted suppliers allows us to respond to the unique needs of our clients, from reducing component shortages to achieving significant cost savings. Our robust supplier management system and two state-of-the-art quality assurance centres in Shenzhen and Hong Kong ensure that we deliver reliable, traceable procurement services.

At Briocean, quality is our cornerstone. Our commitment is to ensure that every component we source is of the highest quality.

Summary

Category	Trend
Macroeconomics	- U.S. Tightens Tariffs and Export Controls: Systemic Risks for Technology-Intensive and High-Value Industries - U.S. Government Invests $8.9 Billion in Intel, Acquiring Approximately 9.9% Passive Stake to Strengthen Domestic Semiconductor Leadership - Japan Provides Massive Subsidies to Memory Projects, Securing High-End Memory and Advanced Packaging Capabilities - Semiconductors Drive South Korean Exports; Government Plans Support Policies Amid External Tariff Pressure - China Tightens Oversight; Compliance and Local Substitution Advance in Parallel
Industry	Short-term - Samsung / Micron DRAM and NAND Contract Prices Surge - NVIDIA / Intel Equity Cooperation and Joint AI / x86 Platform - Micron Reports Q4 FY2025 Earnings and Guides for Growth - Analog Devices Reports Q3 FY2025 Earnings and Exceeds Expectations - SK Hynix Negotiates Price Adjustments with Customers over AI-Driven Memory Shortage Mid-term - Broadcom Lands US$1 Billion AI Chip Order; Microchip, Deca, and SST Announce NVM Chiplet Collaboration - GigaDevice and iSOFT Infrastructure Software Form Strategic Partnership - Chipsea Technology Reports H1 2025 Revenue Growth and Focus on Full-Stack AI Solutions - Renesas Launches Next-Generation High-Performance Motor Control MCU (RA8T2) - Moore Threads IPO Approved, Raising RMB 8 Billion to Boost AI / GPU / SoC R&D Long-term - SK Hynix Completes World's First HBM4 Development and Initiates Mass Production - TSMC Launches Construction of 1.4nm Process Fab

Category	Trend
End-market	- Artificial Intelligence: AI Chip Startup Groq Raises $750 Million; NVIDIA Plans Up To $100 Billion Investment In OpenAI To Expand AI Data Centers - New Energy: Sungrow Plans To Build 10GW Energy Storage Battery Factory In Egypt; Tesla Granted Approval To Test Autonomous Vehicles In Arizona - Consumer Electronics: Apple's Fall Event Launches iPhone 17 Series As Scheduled; ABB Smart Buildings Reaches Strategic Cooperation With Lesso Group - Industrial: Inovance Launches Four Major Architectures, Reshaping the Underlying Logic of Smart Manufacturing - Automotive: Great Wall V6 Cannon Officially Launches, Featuring 3.0T V6 Twin-Turbo Power - Telecommunications: All Three Chinese Major Carriers Have Laid Out eSIM Smartphone Services - Medical Equipment & Devices: Philips & Masimo Announce Innovative Collaboration to Advance Patient Monitoring Measurement Technology
Component Pricing & Product Insights	- Memory Chips: Demand Drives Industry-Wide Price Increases, AI Edge Storage Solutions Accelerate Iteration - MCU: MCU Demand in Consumer, Appliance, Industrial, and Automotive Markets Shows Moderate Recovery - CPU: Diverging Trends in Server and Consumer CPU Markets

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Macro Environment Updates

1. Macro Environment Overview

1.1 Industry Policy

1.1.1 U.S. Tightens Tariffs and Export Controls: Systemic Risks for Technology-Intensive and High-Value Industries

(A) New Tariff Measures: On September 25, 2025, U.S. President Donald Trump announced that, effective October 1, a 100% tariff will be imposed on imported branded and patented pharmaceuticals. Companies that have already commenced construction of U.S. manufacturing facilities are exempt. In addition, tariffs of 50% will apply to kitchen and bathroom cabinets, 30% to upholstered furniture, and 25% to heavy-duty trucks. These measures reflect a closer alignment of U.S. tariff policy with national security objectives and the goal of revitalizing domestic manufacturing.

B) Export Control Escalation: In late August and early September 2025, the U.S. Department of Commerce formally revoked the "Validated End-User" (VEU) status for certain Samsung and SK hynix facilities in China. Going forward, these companies will need to obtain export licenses to expand capacity or implement technological upgrades in these plants, with a 120-day lead time before approvals take effect. Similarly, the fast-track (VEU) export status of TSMC's Nanjing facility has also been revoked and will be fully cancelled by the end of 2025.

These developments indicate a multi-pronged U.S. strategy—combining tariffs and export controls—to tighten oversight of supply chains, security, and industrial policy. For the semiconductor and high-tech sectors, this translates into higher compliance costs and increased procedural complexity for product imports and equipment procurement. Companies aiming to maintain production and technology upgrades at overseas facilities may face stricter licensing requirements and potential delays. In high-value or technology-sensitive areas, demonstrating "local production" or "onshore manufacturing capability" may become a critical condition for market access and policy support.

1.1.2 U.S. Government Invests $8.9 Billion in Intel, Acquiring Approximately 9.9% Passive Stake to Strengthen Domestic Semiconductor Leadership

On August 22, 2025, the U.S. government reached an agreement to purchase $8.9 billion in Intel common stock, acquiring a 9.9% stake at $20.47 per share. Approximately $5.7 billion of this investment is sourced from unpaid grants under the CHIPS and Science Act, and $3.2 billion from the Secure Enclave national security program. The government has stated that this investment is passive, with no board seats or governance rights. The move aims to enhance U.S. competitiveness in high-end semiconductor logic processors and manufacturing, ensuring self-sufficiency in critical supply chains. This shift from traditional subsidies to equity participation influences capital allocation, risk assessment, and companies' cost–benefit considerations for U.S.-based production or joint ventures. In the long term, market expectations will increasingly factor in an active government role in semiconductor firms, particularly regarding financing, capacity expansion, and technology partnerships.

1.1.3 Japan Provides Massive Subsidies to Memory Projects, Securing High-End Memory and Advanced Packaging Capabilities

In September 2025, Japan's Ministry of Economy, Trade and Industry (METI) confirmed it will provide up to JPY 536 billion (approximately $3.6 billion) in subsidies to Micron for constructing next-generation DRAM/HBM production lines in Hiroshima. The funding supports factory construction, advanced process technology (targeting 1-gamma), and advanced packaging and R&D facilities, with production planned for 2027. This subsidy reflects Japan's concrete actions in the global subsidy race, aiming to rebuild domestic capabilities in high-end memory and packaging. Direct industrial effects include short-term boosts to equipment, materials, and packaging tenders, and medium-to-long-term shifts in regional memory capacity distribution that could impact South Korean and Taiwanese production and pricing. Equipment and material suppliers are advised to engage actively with Japanese tenders and local government support, while chipmakers should evaluate local supply chain partnerships to leverage policy benefits.

1.1.4 Semiconductors Drive South Korean Exports; Government Plans Support Policies Amid External Tariff Pressure

In September 2025, South Korea released trade data showing semiconductor exports in August rose 27.1% year-over-year to $15.1 billion, driving overall exports up 1.3% for the month, marking the third consecutive month of positive growth. Despite a 12% decline in U.S. exports due to American tariffs, tariff-exempt products such as semiconductors continued steady growth. In response, the Ministry of Trade, Industry and Energy indicated that multiple support policies will be introduced, including increased subsidies for small and medium exporters, market diversification initiatives, and measures to enhance product competitiveness and cost efficiency, aimed at mitigating the impact of tariffs and trade friction on the export environment.

1.1.5 China Tightens Oversight; Compliance and Local Substitution Advance in Parallel

In September 2025, Chinese regulators maintained a strict stance on compliance and “information security” risks for imported high-end AI computing products. Agencies including the Cyberspace Administration of China and industry regulators engaged with several internet and computing service companies in August–September regarding purchases of foreign high-performance AI chips, such as NVIDIA models. They emphasized the need to evaluate information security and locally developed alternatives, while encouraging policy and financial support to accelerate the industrialization and commercialization of domestic AI chips and accelerators.

This approach reflects industrial security considerations and signals support for local substitution and upstream supply chain localization. In the short term, it may curb large-scale procurement of foreign high-end GPUs by Chinese enterprises; in the long term, it is expected to accelerate the development of locally developed AI chips and strengthen the domestic IP ecosystem.

1.2 Economic Indicators

1.2.1 Global Manufacturing PMI Rises to 50.9% in August; Regional Recovery Divergence Impacts Semiconductor Demand

In August 2025, the global manufacturing Purchasing Managers' Index (PMI) rose to 50.9%, up from 49.7% in July, indicating a modest rebound in global manufacturing activity—the highest level in 14 months. However, regional performance diverged significantly, reflecting uneven global economic recovery.

China: Manufacturing PMI in August was 49.4%, slightly up from 49.3% in July, indicating continued contraction in manufacturing activity, though at a slower pace.

Japan: August PMI rose to 49.7% from 48.9% in July, suggesting slight improvement in manufacturing activity, but still in contraction territory.

South Korea: August PMI increased slightly to 48.3% from 48.0% in July, with manufacturing activity remaining in contraction, weighed down by weak external demand.

India: Manufacturing PMI stood at 59.3% in August, up from 59.1% in July, reflecting strong expansion and robust demand in the sector.

U.S.: PMI rose to 48.7% in August from 48.0% in July, showing improvement in manufacturing activity, with growth in production and new orders.

Eurozone: Manufacturing PMI increased to 50.7% in August from 49.8% in July, indicating mild expansion in manufacturing activity, though business sentiment remains weak.

Overall, global manufacturing recovery shows clear regional divergence: emerging markets such as India exhibit strong expansion; Europe and the U.S. show moderate improvement; while major Asian economies like China, Japan, and South Korea continue to face contraction. This regional disparity highlights the uneven nature of the global economic recovery, signaling that businesses should monitor national economic policies and international trade conditions, and adapt strategies to different market challenges.

Global Manufacturing by Region PMI

Period	Global	China	Japan	Korea	India	Americas	Eurozone
2023-11	49.30	49.40	48.30	50.00	56.00	46.70	44.20
2023-12	49.00	49.00	47.90	49.90	54.90	47.40	44.40
2024-01	50.00	49.20	48.00	51.20	56.50	49.10	46.60
2024-02	50.30	49.10	47.20	50.70	56.90	47.80	46.50
2024-03	50.60	50.80	48.20	49.80	59.10	50.30	46.10
2024-04	50.30	50.40	49.60	49.40	58.80	49.20	45.70
2024-05	50.90	49.50	50.40	51.60	57.50	48.70	47.30
2024-06	49.50	49.50	50.00	52.00	58.30	51.70	45.60
2024-07	49.80	49.40	49.10	51.40	58.10	46.80	45.80
2024-08	48.90	49.10	49.80	51.90	57.50	47.20	45.60
2024-09	48.80	49.80	49.70	48.30	56.50	47.20	45.00
2024-10	48.80	50.10	49.80	48.30	57.50	46.50	46.00
2024-11	50.00	50.30	49.00	50.60	56.50	48.40	45.20
2024-12	49.60	50.10	49.60	49.00	56.40	49.20	45.10
2025-01	50.10	49.10	48.70	50.30	57.70	50.90	46.60
2025-02	50.60	50.20	49.00	49.90	56.30	50.30	47.60
2025-03	50.30	50.50	48.40	49.10	58.10	49.00	48.60
2025-04	49.80	49.00	48.70	47.50	58.20	48.70	49.00
2025-05	49.60	49.50	49.40	47.70	57.60	48.50	49.50
2025-06	50.30	49.70	50.10	48.70	58.40	49.00	50.50
2025-07	49.70	49.30	49.90	48.00	59.20	48.00	49.80
2025-08	50.90	49.40	49.90	48.00	59.30	48.70	50.70

Source : Wind

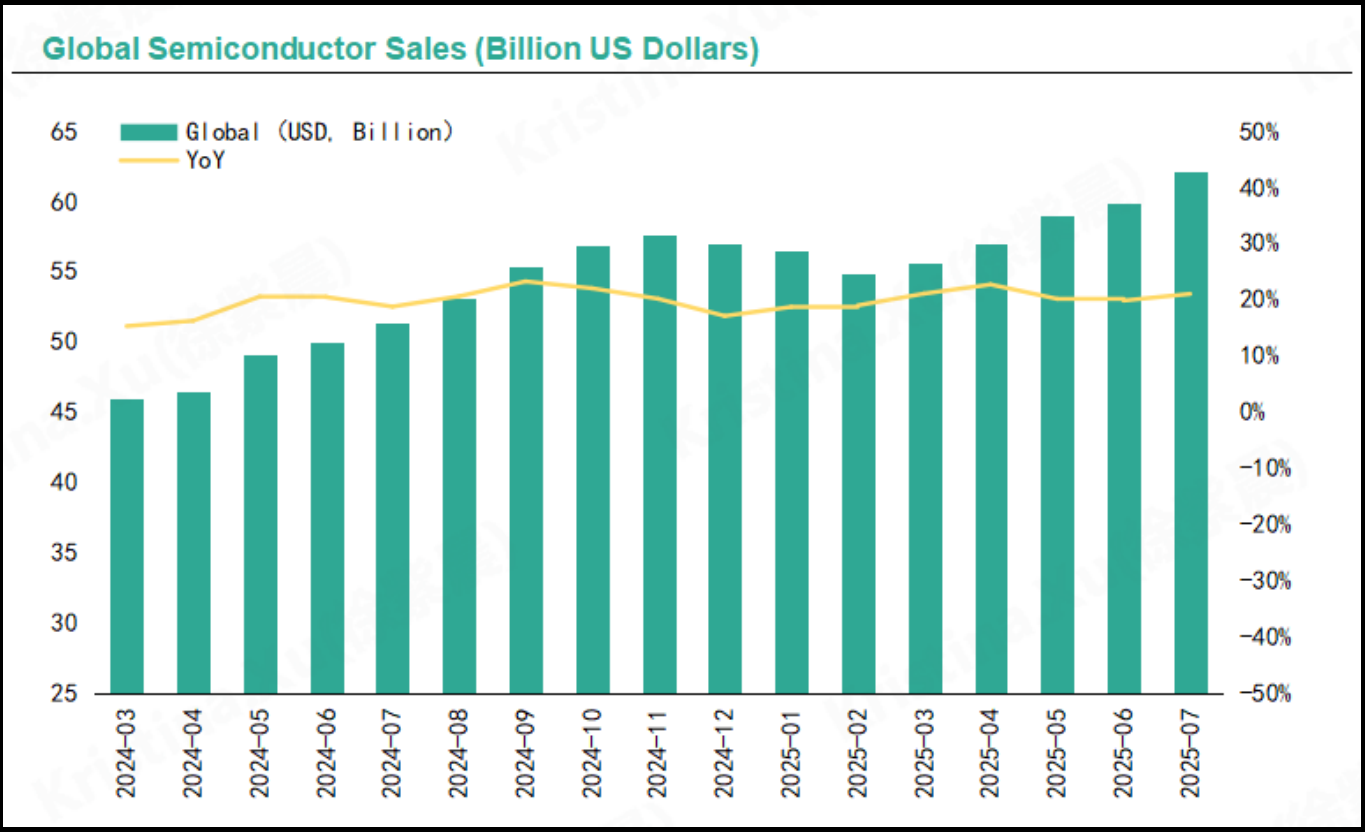
1.2.2 Global Semiconductor Sales Up 20.6% YoY in July; Strong Performance in Asia-Pacific and Americas

In July 2025, global semiconductor sales reached USD 62.1 billion, up 20.6% year-on-year (YoY) and 3.6% month-on-month (MoM). This growth was primarily driven by strong performance in the Asia-Pacific and Americas markets. Sales in Asia-Pacific and other regions rose 35.6% YoY, while the Americas grew 29.3%, and the China market increased 10.4%, reflecting robust growth across the global semiconductor market. In contrast, the Japanese market declined 6.3% YoY, indicating relative weakness in that region.

MoM data also show positive trends: sales in Asia-Pacific and other regions increased 4.9%, the Americas rose 8.6%, China declined 1.3%, and Japan decreased 0.2%. These figures suggest that, despite regional variations, the overall semiconductor market continues to expand.

It is notable that, despite significant global growth, the Japanese market remains relatively weak, potentially affected by subdued domestic demand and international trade uncertainties. Looking ahead, global semiconductor growth may be influenced by geopolitical and trade policy developments, particularly amid ongoing trade tensions between the U.S. and China.

Overall, July 2025 sales data reflect strong growth in the global semiconductor market, especially in Asia-Pacific and the Americas. With continued demand from AI, data centers, and high-performance computing, the global semiconductor market is expected to maintain its growth momentum in the second half of the year.



Source：SIA

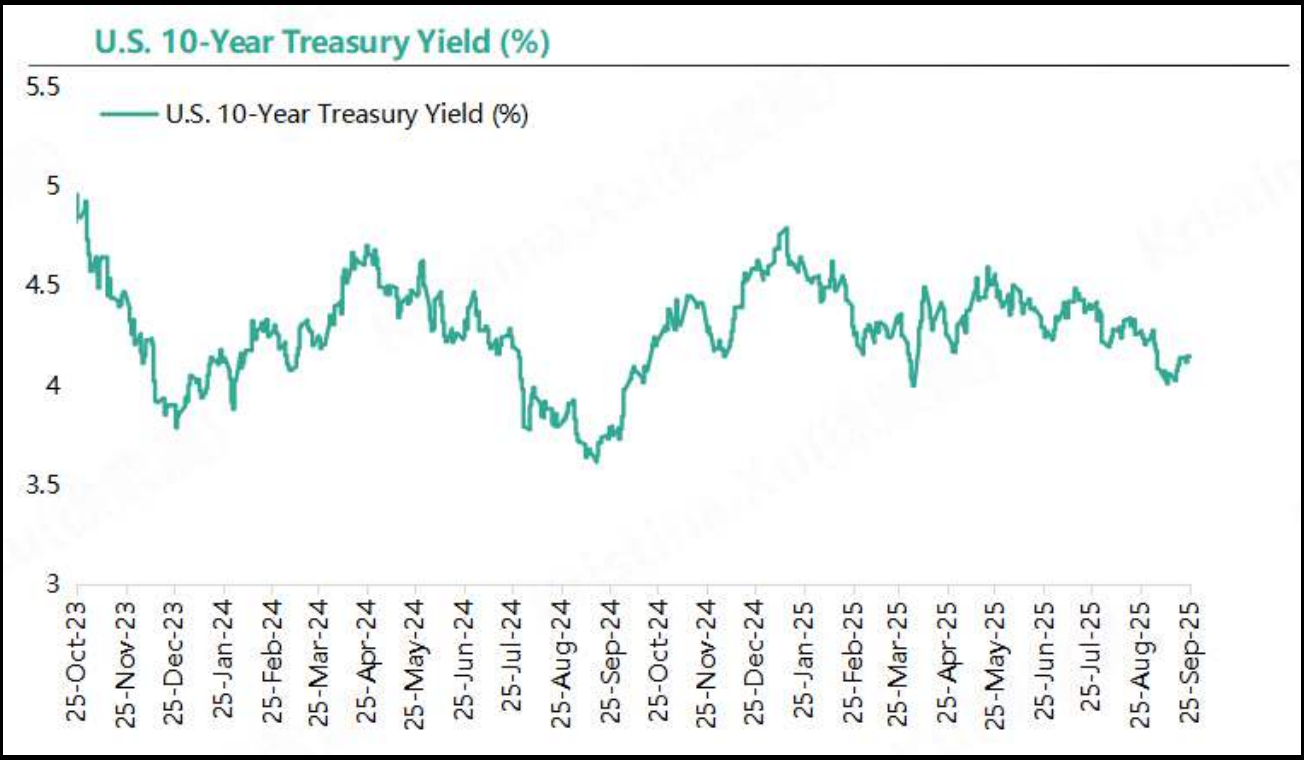
1.2.3 U.S. 10-Year Treasury Yield: Mid-September Breaks Above 4.10%, Curve Shape Signals Policy Expectation Divergence

As of late September 2025, the U.S. 10-year Treasury yield remained volatile in the 4.10%–4.15% range, reflecting market caution over the economic outlook. On September 24, the 10-year yield edged up to 4.1447%, an increase of 3.85 basis points from the previous trading day. On the same day, the 2-year Treasury yield also rose by 1.40 basis points, closing at 3.6000%.

Recent U.S. economic data have been mixed, shaping market expectations for future monetary policy. New home sales in August reached an annualized 800,000 units, up 20.5% month-on-month, far exceeding forecasts and signalling strong momentum in the housing market. However, nonfarm payrolls in August added only 22,000 jobs, with the unemployment rate rising to 4.3%, underscoring weakness in the labor market. In addition, both the Consumer Price Index (CPI) and Producer Price Index (PPI) for August indicated rising inflationary pressures, further increasing uncertainty around the Federal Reserve's policy path.

On September 17, the Federal Reserve lowered the federal funds rate by 25 basis points to 4.00%–4.25% and signaled the possibility of further rate cuts to counter slowing growth and inflation pressures. Nevertheless, the housing market's strength may make the Fed more cautious in delivering additional cuts. Investors are now closely watching the upcoming Personal Consumption Expenditures (PCE) price index release to gauge inflation trends and the Fed's future policy direction.

Overall, the U.S. 10-year Treasury yield remained elevated and range-bound through September, reflecting market concerns over slowing economic growth and persistent inflation pressures. Investors will need to monitor upcoming economic data closely to assess the trajectory of Federal Reserve policy.



Source : Investing

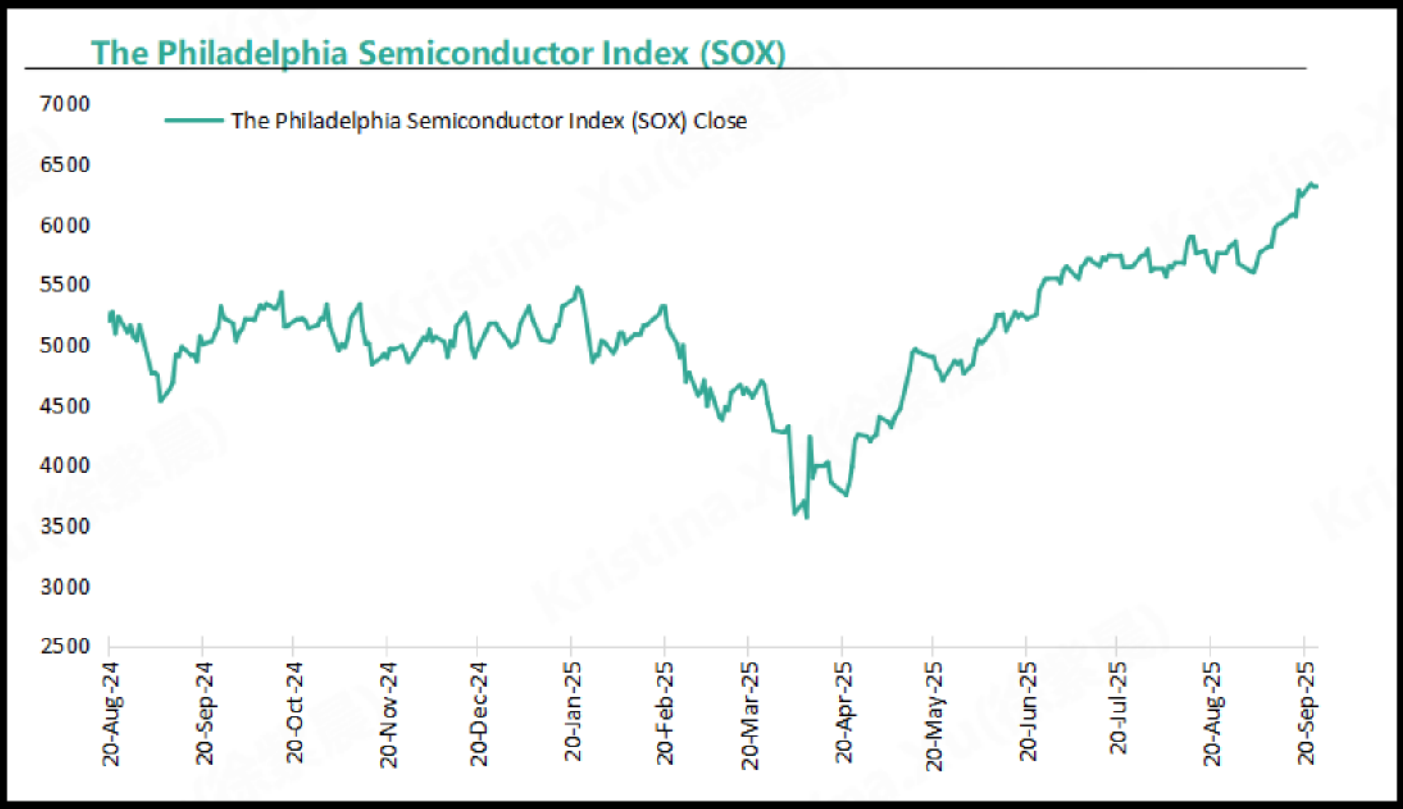
1.2.4 Philadelphia Semiconductor Index Trend in August–September: Rate Cuts and Strategic Partnerships Propel Chip Stocks to Record Highs

In August–September 2025, the Philadelphia Semiconductor Index posted strong gains, supported by both Federal Reserve monetary easing and major industry strategic partnerships. The index climbed steadily from around 5,600 points in mid-August to 6,244.53 points on September 25, marking an increase of nearly 10% and significantly outperforming the broader market.

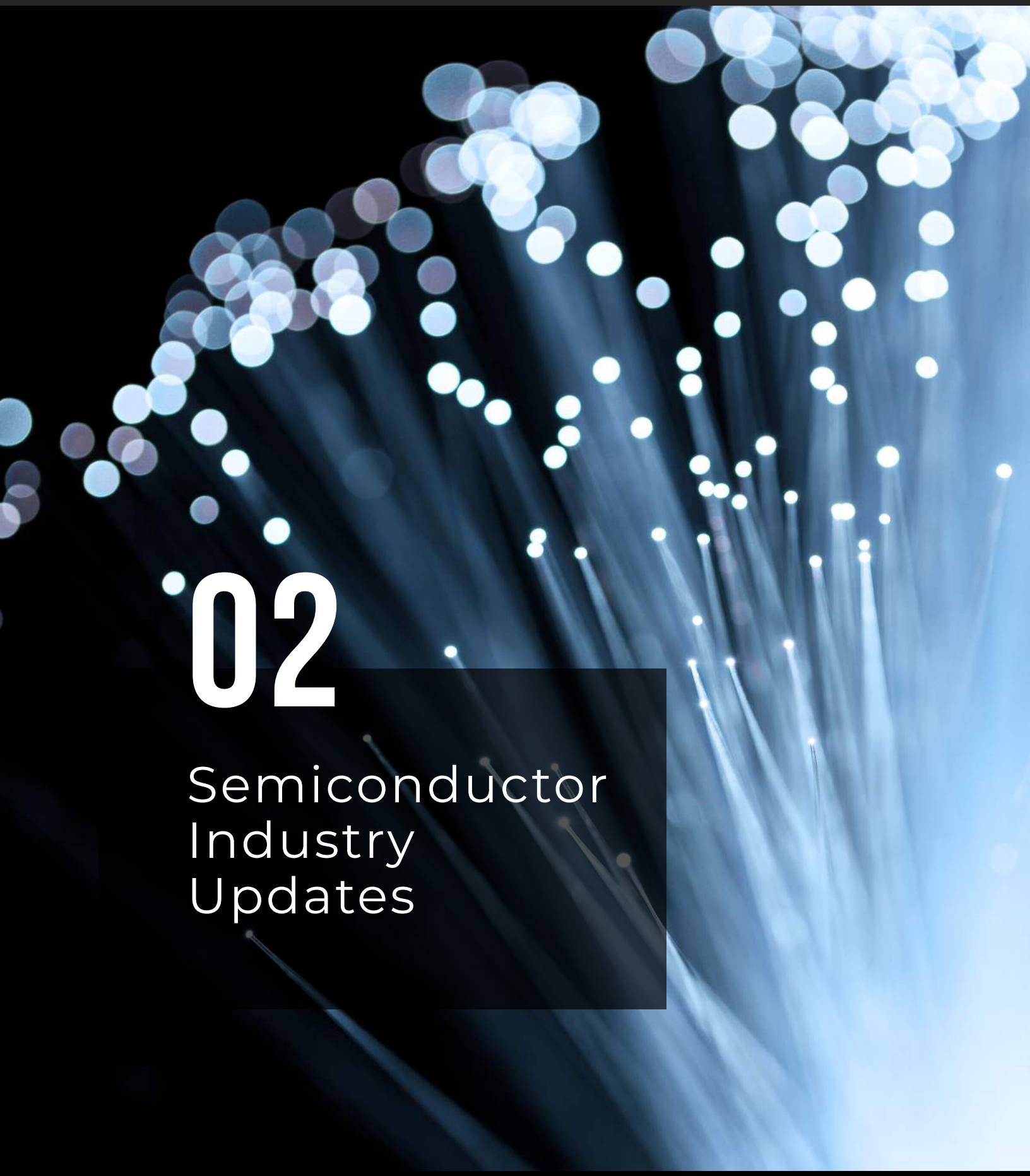
Mid-September marked a key turning point. On September 18, the index surged 3.6% in a single session, reaching an all-time high. This breakout was driven by two major factors: NVIDIA's announcement of a USD 5 billion investment in Intel as part of a deep strategic collaboration, and the Federal Reserve's first rate cut of 2025. Intel's share price soared 22.77% that day—the largest single-day gain since 1987—while equipment makers such as ASML and Applied Materials, Inc. each rose more than 6%.

Policy shifts and market expectations jointly supported the rally. In September, the Federal Reserve cut the federal funds rate by 25 basis points, signaling a pivot toward supporting economic growth. Citi, Goldman Sachs, and other institutions forecast additional 25-basis-point cuts in both October and December, with such expectations providing sustained liquidity support for technology stocks. Although a technical correction emerged in late September, the semiconductor sector remained fundamentally supported by AI-driven demand and deepening supply chain collaboration.

Overall, the Philadelphia Semiconductor Index's performance in August–September reflects the prosperity of the global semiconductor industry under the dual drivers of technological innovation and favorable policy, with markets maintaining an optimistic outlook for long-term industry growth.



Source : MacroMicro



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Semiconductor Industry Updates

Semiconductor Industry Overview

Impact	Manufacturer	Updates	Analysis
Short-term	Samsung Micron	DRAM and NAND Contract Prices Surge	The sharp upward adjustment in mobile DRAM and NAND pricing underscores supply–demand tightness, with downstream OEM customers set to face higher costs
	NVIDIA Intel	Equity Cooperation and Joint AI / x86 Platform	The investment and cooperation enhance market confidence in Intel's transformation and manufacturing capability revival, and also reflect NVIDIA's extension in system platform strategy
	Micron	Reports Q4 FY2025 Earnings and Guides for Growth	AI-driven memory demand is surging, revenue has risen sharply, and guidance was raised, reflecting tightening supply-demand conditions in memory chips
	Analog Devices	Reports Q3 FY2025 Earnings and Exceeds Expectations	Revenue reaches US$2.88 billion, up by double-digits YoY; demand stable across end markets; diversification proving resilient
	SK hynix	Negotiates Price Adjustments with Customers over AI-Driven Memory Shortage	AI demand has triggered DRAM/NAND supply constraints, and SK Hynix is following industry peers in pushing for price increases to ease supply-demand tensions

Impact	Manufacturer	Updates	Analysis
Mid-term	Broadcom	Lands US$1 Billion AI Chip Order	Custom AI chip deal with a new major client underlines Broadcom's new role in the AI accelerator market and boosts expectations for performance growth
	Microchip	Announce NVM Chiplet Collaboration	Three parties jointly launch an NVM chiplet solution, accelerating the development of memory solutions for multi-chip architectures
	GigaDevice	GigaDevice and iSOFT Infrastructure Software Form Strategic Partnership	Collaboration with a local automotive OS provider, combining automotive-grade MCUs and domestic automotive operating systems, jointly advancing the domestic automotive electronics ecosystem
	Chipsea	H1 2025 Revenue Growth and Focus on Full-Stack AI Solutions	The half-year report shows steady revenue growth, with continued investment in AI and the development of a full-stack "Chip + Algorithm + Scenario + App + AI" solution
	Renesas	Launches Next-Generation High-Performance Motor Control MCU (RA8T2)	The launch of the 1 GHz + 250 MHz dual-core MCU, aimed at industrial automation and robotics, strengthens its competitiveness in the motor control field
	Moore Threads	IPO Approved, Raising RMB 8 Billion to Boost AI / GPU / SoC R&D	IPO approval signals market recognition for domestic GPUs and accelerating product development and ecosystem validation, though R&D spending is high and losses remain a risk

Impact	Manufacturer	Updates	Analysis
Long-term	SK hynix	Completes World's First HBM4 Development and Initiates Mass Production	Announced the world's first HBM4 development, doubling bandwidth and improving energy efficiency by 40%, establishing a leading position in AI memory technology
	TSMC	Launches Construction of 1.4nm Process Fab	Announced Q4 construction of a 1.4nm fab, investing US$16.5 billion, further consolidating its global leadership in advanced process technology

2. Semiconductor Industry Updates

2.1 Short-term Implications

2.1.1 Samsung Electronics / Micron DRAM and NAND Contract Prices Surge

Recent industry reports indicate that Samsung Electronics has notified key customers of significant price increases for DRAM and NAND Flash contracts in Q4. Mobile DRAM (including LPDDR4X, LPDDR5/5X) is expected to rise by 15–30%, while NAND storage (eMMC, UFS, etc.) is projected to increase by 5–10%. At the same time, Micron has suspended quotations across several channels and signaled that its DRAM and NAND products will see price hikes of around 20–30%.

This reflects sustained demand growth for memory capacity and bandwidth in AI data centers, high-performance computing, and mobile devices, while supply expansion and inventory levels have yet to fully catch up. In the short term, downstream smartphone makers and system vendors will face rising costs, potentially opting to secure procurement earlier or adjust product positioning to absorb the impact. For memory suppliers, this represents an opportunity to improve bargaining power and profit margins. In the medium term, the market may enter an upward price cycle, with tighter supply and higher prices for legacy/low-density NAND and lower-end DRAM. Manufacturers are likely to prioritize investments in high-density and premium product lines to maximize profitability.

Over the long term, if the price hikes persist and gain broad acceptance among end markets and competitors, the industry's memory technology adoption curve may be reshaped—enhancing the competitiveness of high-value categories such as HBM and high-stack 3D NAND—while exerting a lasting influence on memory and system cost structures. Key factors to monitor include whether customers can absorb the cost increases without dampening demand, and whether capacity expansion and materials supply can keep pace.

2.1.2 NVIDIA / Intel Equity Cooperation and Joint AI / x86 Platform

In mid-September 2025, NVIDIA announced an investment of about US$5 billion in Intel common stock, accounting for about 4% of Intel's shares, and reached a cooperation agreement to jointly develop AI accelerators and x86 CPU platforms. According to the announcement, this includes combining NVIDIA's accelerator/NVLink technology with Intel's CPU architecture for data center and PC SoC products. In the short term, the impact is reflected in Intel's stock price rising sharply, which is regarded as market recognition of its technology and manufacturing capabilities; NVIDIA has obtained stronger influence at multiple platform levels and greater supply chain stability. In the medium term, this cooperation may help Intel accelerate product iteration and competitiveness recovery in high-performance and AI chips, while NVIDIA can also expand its market boundaries in x86/PC + AI integrated products through this cooperation. In the long term, this may signify the deepening of joint efforts and platform-based competition among U.S. chip companies in the AI hardware ecosystem: it is expected to counter the leading position of foundries (such as TSMC, Samsung) in manufacturing and design, and reshape the computing platform pattern in the era of artificial intelligence. Key observation points include: the progress of technology integration (CPU-GPU chip integration, NVLink efficiency), transparency of the product roadmap, progress of regulatory approval, and whether the distribution of interests and capacity commitments in the cooperation match market expectations.

2.1.3 Micron Reports Q4 FY2025 Earnings and Guides for Growth

After market close on September 24, 2025, Micron Technology announced results for the fourth quarter of fiscal year 2025 (ended August 28). The report showed quarterly revenue of US$11.32 billion, up 46% year-on-year, with adjusted earnings per share far exceeding analyst expectations. In the earnings call, Micron emphasized benefits from AI-driven memory demand growth, especially the sustained strength in high-bandwidth memory (HBM). CEO Sanjay Mehrotra stated that current HBM capacity has been fully booked, and shipments in fiscal year 2026 are expected to grow faster than overall DRAM, becoming the core growth driver for the memory business. Micron also issued strong guidance, projecting Q1 FY2026 revenue of US$122.0–128.0 billion, above market expectations. This reflects the sharp pull from AI applications and data center upgrades on memory demand, as well as price increases driven by supply-demand tightness (with industry peers simultaneously entering price negotiations amid the AI boom). Overall, Micron's quarterly performance was outstanding, indicating that its supply capacity in the global memory market and the rigid AI-driven demand significantly boosted short-term results, providing a clear uplift to both company performance and the short-term industry landscape.

2.1.4 Analog Devices Reports Q3 FY2025 Earnings and Exceeds Expectations

In September, Analog Devices released its Q3 FY2025 earnings showing revenue of US$2.88 billion, up by double-digit percentage year-over-year; operating cash flow was strong, at US$462 million. Also, the company's performance surpassed expectations, and management indicated demand is stable across its business segments—both revenue and earnings per share exceeded prior guidance. ADI's leadership noted growth across multiple end markets including automotive, communications, and industrial, with orders ample and a diversified product mix and customer base helping stabilize results. The company also expects Q4 revenue to remain around US$300 million, with margins staying at high levels. ADI's performance highlights its stable market position and product competitiveness, indicating a short-term rebound in demand for analog and embedded markets. Industry observers believe the result reflects enduring demand for analog chips in automotive electronics, industrial automation, etc., and that the company's diversified strategy and technological leadership enable it to sustain growth even in a complex economic environment.

2.1.5 SK Hynix Negotiates Price Adjustments with Customers over AI-Driven Memory Shortage

As AI data center build-out accelerates and demand for high-performance DRAM and NAND surges, multiple storage giants have begun pushing for higher chip prices. According to market research firms, following Micron and Samsung's disclosed memory price increase plans, SK Hynix is currently negotiating price adjustment policies with its customers.

Reports say that the current DRAM supply tightening is largely because manufacturers are prioritizing wafer production for high-bandwidth memory (HBM), and the AI inference and data center refresh demands are further worsening supply-demand imbalance. While SK Hynix has not officially announced a price increase, it is exploring options to raise prices in accordance with prevailing market conditions.

This behavior indicates that under the AI wave, the memory market is entering a phase of supply shortages; in the near term, DRAM and SSD prices are expected to continue rising. For SK Hynix, price uplift measures may improve gross margins, though they could also dampen end-market demand. Upstream in the supply chain, equipment vendors could benefit from inventory replenishment.

2.2 Mid-term Implications

2.2.1 Broadcom Lands US$1 Billion AI Chip Order

On September 5, 2025, Broadcom announced it had received a custom order for AI accelerator chips valued at approximately US$1 billion (according to media reports, the customer is likely OpenAI). After the announcement, Broadcom's stock price jumped about 15%, setting a new high. This order marks a key milestone for Broadcom's custom ASIC business, signifying a major breakthrough in the AI-specific chip space. Previously, the company had announced collaborations with AI leaders to develop dedicated accelerators; this large contract further solidifies its position as a supplier of AI infrastructure. Industry insiders say such large, customized orders show Broadcom's growing competitiveness in the data center/high-performance computing market, and are expected to drive growth in its upcoming fiscal years.

2.2.2 Microchip, Deca, and SST Announce NVM Chiplet Collaboration

On September 10, 2025, Microchip Technology announced a strategic collaboration with packaging company Deca and memory supplier Silicon Storage Technology (SST) to jointly develop a non-volatile memory (NVM) chiplet solution. The solution integrates Deca's fan-out packaging technology with SST's SuperFlash memory technology, forming the foundation for a modular, multi-die package architecture. The collaboration aims to provide "chip-level" flash for multi-chip systems, enabling flexible deployment across various applications. This move reflects growing industry demand for chiplet architectures, while Microchip leverages the partnership to expand its capabilities in storage and packaging technologies. The collaboration is expected to accelerate next-generation memory chip design innovation, enhance system performance and integration, and strengthen Microchip's competitive position in the high-performance NVM market.

2.2.3 GigaDevice and iSOFT Infrastructure Software Form Strategic Partnership

On September 2, 2025, Chinese chipmaker GigaDevice and automotive OS provider iSOFT Infrastructure Software Co., Ltd. announced a strategic partnership at the China Automotive Chip Conference. The collaboration will focus on GigaDevice's automotive-grade MCU chips and iSOFT's AUTOSAR-based automotive software platform, aiming to jointly develop safe and reliable automotive electronic hardware-software solutions. This initiative aligns with national efforts to promote localization in automotive electronics. By integrating hardware and software, the partnership lowers the barriers for domestic adoption and accelerates the development of the smart connected vehicle ecosystem. Industry observers note that this move strengthens GigaDevice's competitiveness in the automotive MCU sector, and working with a software provider helps create a complete domestically sourced solution, positively contributing to the self-sufficiency of China's automotive electronics supply chain.

2.2.4 Chipsea Technology Reports H1 2025 Revenue Growth and Focus on Full-Stack AI Solutions

On August 19, 2025, Chipsea Technology disclosed its half-year results, reporting revenue of RMB 374 million in H1, up 6.8% year-on-year, and a net loss attributable to shareholders of RMB 38.828 million, improving 31.7% year-on-year.

The company attributed the performance improvement to scaled shipments of Battery Management System (BMS) products, growth in wearable PPG business from top-tier clients, and rapid expansion of human-machine interaction products for smartphone customers. Chipsea continues to increase investment in AI, deeply integrating analog signal chain and MCU platform technologies, aiming to build a full-stack solution encompassing "Chip + Algorithm + Scenario + App + AI." Through product innovation and operational optimization, the company enhances performance resilience while actively expanding in core markets such as AIoT, automotive electronics, and industrial control. This strategic approach demonstrates Chipsea's use of AI to penetrate multiple industry applications, strengthening its competitiveness in analog and mixed-signal chips.

2.2.5 Renesas Launches Next-Generation High-Performance Motor Control MCU (RA8T2)

On September 25, 2025, Japan's Renesas Electronics released the RA8T2 series microcontrollers, integrating a 1 GHz Arm Cortex-M85 core and a 250 MHz Cortex-M33 dual-core processor. The RA8T2 targets high-end motor control applications such as factory automation and robotics, significantly enhancing digital signal processing and machine learning performance. The new chip also features multiple Gigabit Ethernet MACs and a dual-port EtherCAT slave interface to support high-bandwidth industrial network communication. In addition, the RA8T2 uses high-density MRAM non-volatile memory to improve speed and durability. Company executives noted that this series continues Renesas' technological leadership in motor control, enabling customers to achieve real-time control and communication functions on a single chip. The release highlights Renesas' market positioning for Industry 4.0 and smart manufacturing upgrades and is expected to drive growth in related business areas.

2.2.6 Moore Threads IPO Approved, Raising RMB 8 Billion to Boost AI / GPU / SoC R&D

On September 26, Moore Threads Intelligent Technology (Beijing) passed the Science and Technology Innovation Board IPO review at the Shanghai Stock Exchange, planning to raise RMB 8 billion for R&D of AI training/inference chips, GPU chips, and AI SoC chips, as well as to supplement working capital. Since its founding in 2020, the company's revenue has grown from approximately RMB 46 million in 2022 to RMB 438 million in 2024, reaching around RMB 702 million in H1 2025, showing a rapid growth trend. Although cumulative losses exceed RMB 5 billion and R&D spending is substantial, the IPO approval marks capital recognition for its domestic GPU/AI infrastructure efforts and represents a new stage of technological investment. In the short term, the IPO boosts industry and market confidence; in the medium term, it will accelerate product R&D and ecosystem adaptation; in the long term, narrowing the gap with international GPU vendors in performance, power efficiency, and ecosystem compatibility remains a key observation point.

2.3 Long-term Implications

2.3.1 SK Hynix Completes World's First HBM4 Development and Initiates Mass Production

On September 12, 2025, SK Hynix announced the completion of the world's first fourth-generation high-bandwidth memory (HBM4) and has entered mass production preparation. Compared with the previous generation, HBM4 doubles bandwidth and improves energy efficiency by 40%. The technology achieves this by increasing I/O channels to 2,048 bits, using advanced packaging and 1b nanometer process, delivering transfer rates and efficiency well beyond industry standards. Company management stated that this milestone breaks through AI infrastructure bottlenecks and will significantly enhance AI computing efficiency. Industry consensus holds that SK Hynix's leadership in HBM will solidify its position in the high-end AI memory market. In the long term, HBM4's mass production readiness is expected to ease bandwidth pressure in AI data centers and drive the development of next-generation servers and AI computing.

2.3.2 TSMC Launches Construction of 1.4nm Process Fab

On September 25, 2025, Taiwan's Taipei Times reported that TSMC plans to begin construction of its latest 1.4nm process wafer fab in Q4, targeting production in 2028, with an estimated investment of NT$500 billion (approximately US$16.5 billion). The project was announced by the Central Taiwan Science Park Administration, indicating TSMC will adopt a more advanced process than originally planned for the new fab. Meanwhile, TSMC is accelerating production preparation for its 2nm and 1.6nm processes, with 2nm mass production planned for this quarter and 1.6nm scheduled for H2 2026 at the southern fab. These initiatives reflect TSMC's strategic acceleration to meet global AI and high-performance computing demand: massive investment in advanced process capacity not only reinforces its market leadership but also generates substantial orders for upstream suppliers. In the long term, this will further strengthen TSMC's technology and scale advantages, supporting continued growth of Taiwan's semiconductor industry.

03

Application Updates

3. Application Updates Overview

Category	Section	Manufacturer	Updates
Artificial Intelligence	AI Chip	Groq	AI chip startup Groq raised $750 million to expand data center capacity, with plans to establish its first Asia-Pacific footprint this year
Artificial Intelligence	Cloud Computing & Big Data	NVIDIA	NVIDIA will invest up to $100 billion in OpenAI to build and deploy at least 10GW of AI data center capacity
New Energy	Photovoltaics & Energy Storage	Sungrow	Sungrow plans to build a 10GW energy storage battery factory in Egypt, supporting the country's strategic goal of localizing the new energy and renewable energy supply chain
New Energy	New Energy Vehicles	Tesla	Tesla was reportedly approved to begin testing autonomous vehicles equipped with safety monitors in Arizona
Consumer Electronics	Smartphones	Apple	Apple's fall event was held as scheduled, launching the AirPods Pro 3, three Apple Watch models, and four iPhone 17 series devices
Consumer Electronics	Robotics	ABB	ABB Smart Buildings and Lesso Group reached strategic cooperation, jointly shaping a new landscape for the smart building electromechanical retail market
Industrial	Industrial Automation & Control	Inovance	Inovance Technology unveiled the four IPMT-led architectures of FA, Motion Control, Drive, and Robotics, covering the full stack from "Design – Manufacturing – Drive – Execution."
Automotive	Automotive Supply Chain	Longhorn Auto	Great Wall V6 Cannon officially launches as a race-grade performance pickup with 3.0T V6 twin-turbo power.

Category	Section	Manufacturer	Updates
Telecommunications	Communication Networks & Optical Fiber	China Unicom	China Unicom is the only supported iPhone eSIM carrier. Ahead of Apple's product launch, China Unicom renamed its official WeChat account from "My eSIM" to "Unicom eSIM."China Mobile awarded an AI inference device centralized procurement project worth ￥5.112 billion , with companies like ZTE among the winners
Medical Equipment & Devices	Medical Imaging Equipment	Philips	Philips & Masimo Announce Innovative Collaboration to Advance Patient Monitoring Measurement Technology

3.1 Artificial Intelligence

3.1.1 AI Chip Startup Groq Raises $750 Million

On September 17, Reuters reported that, amid Wall Street's strong bets on AI hardware, chip startup Groq announced it raised $750 million in its latest funding round, bringing its post-money valuation to $6.9 billion. The round was led by Disruptive, with participation from significant investors including Luminar, DTCP (Deutsche Telekom's venture arm), and existing investors Samsung, D1, and Altimeter. The funds will be used to expand data center capacity, and Groq plans to announce its first Asia-Pacific deployment site later this year.

3.1.2 NVIDIA Plans Up To $100 Billion Investment In OpenAI To Expand AI Data Centers

On September 22, NVIDIA and OpenAI announced a collaboration under which NVIDIA will invest up to $100 billion to support OpenAI in building and deploying at least 10GW of AI data centers for training next-generation models. According to the agreement, OpenAI will deploy AI data centers with a total capacity of 10GW, equipped with 4–5 million NVIDIA GPUs, roughly equivalent to NVIDIA's total 2025 annual shipments. NVIDIA will follow a phased investment approach: the first 1GW data center, based on the Vera Rubin platform, is expected to come online in the second half of 2026, with subsequent investments added over time, potentially totaling $100 billion.

3.2 New Energy

3.2.1 Sungrow Plans To Build 10GW Energy Storage Battery Factory In Egypt

On September 14, Sungrow announced plans to establish an energy storage battery factory in Egypt with an annual capacity of 10GW. This project will directly support Egypt's strategic goal of localizing its new energy and renewable energy supply chain. For Sungrow, this represents a key step in its global expansion. In H1 2025, the company's energy storage system revenue reached CNY 17.803 billion, up 127.78% year-on-year, accounting for 40.89% of total revenue, surpassing its PV inverter business for the first time.

3.2.2 Tesla Granted Approval To Test Autonomous Vehicles In Arizona

On September 20, Tesla was reportedly granted approval to begin testing autonomous vehicles equipped with safety monitors in Arizona, marking a key step in expanding its autonomous taxi services beyond Austin to other cities and states. Previously, Tesla had received approval to test autonomous vehicles in Texas and Nevada. In June, Tesla launched this long-awaited autonomous service to a small group of early users in Austin for the first time.

3.3 Consumer Electronics

3.3.1 Apple's Fall Event Launches iPhone 17 Series As Scheduled

In the early hours of September 10, Apple's highly anticipated fall event took place as scheduled. The company unveiled the AirPods Pro 3, three Apple Watch models, and four iPhone 17 series devices—including the iPhone 17, iPhone Air, iPhone 17 Pro, and iPhone 17 Pro Max—with starting prices of CNY 5,999, 7,999, 8,999, and 9,999, respectively.

3.3.2 ABB Smart Buildings Reaches Strategic Cooperation With Lesso Group

On the afternoon of September 16, ABB Smart Buildings and China Lesso Group held a signing ceremony in Foshan, Guangdong, to formalize their strategic cooperation. The partnership focuses on ABB-branded miniature circuit breakers, switches, sockets, and Siemens-branded switches and sockets, covering sales networks, channel development, and marketing promotion, aiming to jointly expand the adoption of smart building products in the electromechanical retail market.

3.4 Industrial

3.4.1 Inovance Launches Four Major Architectures, Reshaping the Underlying Logic of Smart Manufacturing

At Inovance Technology's September product launch, the four IPMT heads of FA, Motion Control, Drive, and Robotics presented full-stack architectures covering "Design – Manufacturing – Drive – Execution." The four architectures form a complete closed loop: FA provides the data foundation, Motion Control enables data flow, Drive supplies energy-efficient power, and Robotics executes operations. Leveraging over 20 years of industrial control experience, Inovance lowers the threshold for smart manufacturing and, combined with new wireless and explosion-proof servo products, transforms Chinese manufacturing intelligence from a "luxury" into a "standard access."

3.5 Automotive

3.5.1 Great Wall V6 Cannon Officially Launches, Featuring 3.0T V6 Twin-Turbo Power

On September 23, Great Wall Motors officially announced the launch of the V6 Cannon pickup. Positioned as a race-grade performance pickup, the new vehicle is equipped with a 3.0T V6 twin-turbo engine, a part-time four-wheel-drive system, and front and rear differential locks, targeting high-intensity off-road and racing scenarios. Built on the Tank platform, the V6 Cannon features a high-strength steel frame with excellent torsional rigidity. Its short wheelbase and lightweight design (curb weight 2,285 kg) enhance agility and power response, performing particularly well in complex terrains such as deserts and rocky areas.

3.6 Telecommunications

3.6.1 All Three Major Chinese Carriers Have Laid Out eSIM Smartphone Services

In the early hours of September 10, Apple held its fall product launch, with the newly released iPhone Air receiving particular attention. Its ultra-thin design led Apple to eliminate the physical SIM card slot, replacing it with eSIM. Apple noted that, for iPhones in mainland China, China Unicom is the only supported iPhone eSIM carrier. According to China Mobile staff, the company already supports eSIM smartphone services, with service availability to be announced separately. A China Telecom representative told Securities Daily that the company's eSIM smartphone services are fully prepared and are expected to open to users shortly after receiving official commercial trial approval from the Ministry of Industry and Information Technology. Specific service launch dates will be announced in due course.

3.7 Medical Equipment & Devices

3.7.1 Philips & Masimo Announce Innovative Collaboration to Advance Patient Monitoring Measurement Technology

On September 11, Philips and Masimo announced an update to their long-standing strategic partnership, marking a new chapter in their collaboration. The core of this initiative is the integration of Masimo's advanced monitoring technologies—including SET® pulse oximetry, Radius PPG, and a suite of sensor technologies—into Philips' multi-parameter patient monitoring platform. By embedding these capabilities into Philips' monitoring ecosystem, both companies aim to reduce complexity, enhance interoperability, and provide streamlined tools to support timely decision-making and continuity of care.

04

Product Updates

4. Product Updates

4.1 Memory Chips

Storage Chip Market Key Movements (Sep 2025)

Product Category	Price Trend	Lead Time (Weeks)	Supply-Demand Status
DDR4/LPDDR4	Rising	25+	Some Constraints
DDR5/LPDDR5	Rising	Not Specified	Some Constraints
SSD	Rising	6-10	Some Constraints
HDD	Rising	20+	Some Constraints
NAND Flash	Rising	Not Specified	In Equilibrium

Source: EET China, Fusion

4.1.1 Demand Drives Industry-Wide Price Increases, AI Edge Storage Solutions Accelerate Iteration

1) Product Updates

DDR4, LPDDR4X: Prices for DDR4 and LPDDR4X have surged sharply due to DRAM vendors discontinuing older-process DRAM products, forcing customers to accelerate the transition to DDR5 memory. However, as manufacturers prioritize supply toward higher-margin server and AI segments, DDR5 itself faces severe allocation constraints and continued price increases (monthly gains exceeding 4%), keeping the DRAM market robust.

NAND Flash: Enterprise stocking combined with new smartphone launches has fueled strong price momentum for NAND. As AI applications continue to penetrate rapidly and AI infrastructure expands, massive data demands are increasing, highlighting the high potential for enterprise storage applications.

SSD: AI inference is driving structural changes in high-capacity storage demand, with Nearline SSDs seeing rapid uptake. Vendors are expanding QLC SSD output, with utilization expected to rise gradually in 2026. With the expansion of inference AI applications, this demand trend is expected to continue into 2027, leading to tight supply for enterprise SSDs in 2026.

HDD: Desktop HDD demand is rising while vendor supply remains tight. The increased demand is focused on 1TB and 2TB desktop drives, with Seagate and WD experiencing tight supply for small-capacity desktop disks. Vendors are expected to continue raising prices by more than 10% in the next quarter.

2) Market Trends

AI Demand and Market Recovery Support Industry Growth: In September, the storage market was driven by both AI-driven demand growth and the recovery of the traditional storage market. AI large-model training notably boosted demand for DDR5, HBM, and enterprise SSDs, while the impact of weak consumer electronics demand eased. Overall, the market is expected to regain momentum in the second half of the year, with DRAM shipments projected to achieve double-digit growth for the full year.

Overseas Major Vendors' Profitability Continues to Improve; Domestic Storage Module and Niche Storage Performance Expected to Strengthen in H2 2025: Micron's FY25 Q3 revenue and gross margin exceeded guidance, with single-quarter HBM revenue up nearly 50% quarter-on-quarter, while consumer products continued to recover. SK Hynix posted record revenue in 25Q2. Domestic niche storage companies saw continuous improvements in product shipments, with prices rising across categories at varying rates, reflecting marginal performance gains overall.

Driving Intelligent Enterprise Storage Solutions: Market trends in the storage industry will continue to be shaped by high-performance storage, big data, AI applications, cloud computing, edge computing, and data security. Enterprises will require more intelligent, automated, and secure storage solutions to meet growing data demands. The industry is expected to continue evolving toward higher efficiency, intelligence, and security, fostering technological innovation and deeper shifts in market demand.

4.2 MCU

Q3 2025 MCU Lead Time and Pricing Trends

MCU	Manufacturer	Lead Time (Weeks)	Price Trend
8-Bit MCU	Infineon	10-26	Stable
8-Bit MCU	Microchip	4-12	Stable
8-Bit MCU	NXP	13-39	Stable
8-Bit MCU	Renesas	14-18	Stable
8-Bit MCU	STMicroelectronics	10-24	Stable
32-Bit MCU	Infineon	10-26	Stable
32-Bit MCU	Microchip	4-8	Stable
32-Bit MCU	NXP	13-39	Stable
32-Bit MCU	Renesas	14-18	Stable
32-Bit MCU	STMicroelectronics	13-16	Stable

Sources: CEC Electronics, Future Electronics

4.2.1 MCU Demand in Consumer, Appliance, Industrial, and Automotive Markets Shows Moderate Recovery

1) Product Updates

Renesas: Launched the RA8T2 MCU series based on a 1 GHz Arm Cortex-M85 core, optionally paired with a 250 MHz Cortex-M33 coprocessor and equipped with 1 MB MRAM. Key features include dual gigabit Ethernet and EtherCAT support, targeting high-end industrial equipment, robotics, and factory automation applications that demand high computing power and real-time control.

Infineon: Released a full suite of software for its AURIX™ TC4x MCUs, certified for ASPICE CL3 and ISO 26262 ASIL D, including AUTOSAR MCAL and safety libraries. This aims to help customers significantly shorten development cycles for automotive-grade applications, primarily in ADAS and powertrain systems.

Microchip: Introduced the SAMRH707 radiation-hardened microcontroller, compliant with strict aerospace standards (QML/ESCC), based on Arm Cortex-M7, and supporting SpaceWire and other spacecraft interfaces, designed for satellite subsystems, telemetry, and aerospace applications.

2) Market Trends

Rising Market Demand: Downstream segments are expected to see moderate recovery in 2H 2025. Demand increases are noted in white goods, e-bikes, and computer peripheral MCUs, though customer front-loading may be less pronounced than in 1H. Domestic MCU vendors reported generally stable YoY revenue growth in 2Q 2025, with 2H 2025 prices expected to stabilize.

Architectural Diversification: Infineon revealed a roadmap for automotive RISC-V MCUs, targeting mass production in 2028–2029, indicating future MCU platforms may evolve from Arm dominance to coexistence with RISC-V, offering more market choices.

Focus on High Performance and Real-Time Control: Renesas' RA8T2 pushes clock speed to 1 GHz, integrates large-capacity MRAM, and offers rich industrial network interfaces, directly addressing next-generation robotics and smart factory demands for high computing and real-time capabilities.

4.3 CPU

CPU Market Key Movements (Sep 2025)

Product	Model	Manufacturer	Price Trend	Lead Time (Weeks)
Consumer	i5-13400 (10 cores)	Intel	Stable	4-6
Consumer	i7-13700K (16 cores)	Intel	Falling	4-6
Consumer	R5 7600X (6 cores)	AMD	Falling	Within 4 Weeks
Consumer	R7 7800X3D (8 cores)	AMD	Stable	Within 4 Weeks
Consumer	i7-13700H (14 cores)	Intel	Stable	OEM Lead Time 8 Weeks
Consumer	R7 7840HS (8cores)	AMD	Stable	OEM Lead Time 6-8 Weeks
Server	EPYC 9654 (96 cores)	AMD	Rising	8-12
Server	EPYC 8534P (32 cores)	AMD	Stable	8
Server	Xeon Platinum 8480+ (56 cores)	Intel	Falling	8-20
Server	Xeon Silver 4410 (20 cores)	Intel	Stable	4-6

Source：Data compiled from publicly accessible online data

4.3.1 Diverging Trends in Server and Consumer CPU Markets

1) Product Updates

Consumer: In terms of lead times and pricing trends, the consumer market remains weak. Mainstream Intel and AMD consumer CPUs continue to face price declines. Amid sluggish PC shipments, mid-to-low-end CPUs are oversupplied, resulting in softer prices, while mobile CPUs maintain relatively stable pricing and lead times. High-performance gaming processors retain steady prices supported by rigid demand, with slightly longer lead times.

Servers: Driven by AI and cloud computing, server CPU demand is strong but faces competition from other compute chips. AMD's EPYC 9654 (96-core) is particularly notable, with rising prices and lead times of 8–12 weeks. The server CPU market is navigating robust demand alongside price competition, with vendor profitability under pressure and market share battles intensifying.

2) Market Trends

AI as the Core Driver, Competition Enters the "Full-Stack" Ecosystem Stage: User experience is paramount, and embedded AI is becoming standard. Vendors' competition is shifting from hardware specs (e.g., CPU frequency) to seamless AI integration in user experiences, such as local AI assistants in PCs and intelligent safety features in vehicles. Rapid iteration and intuitive, smart, and secure interactive capabilities are required to attract consumers.

Efficiency and Ecosystem Determine Success: The market is moving from general-purpose procurement to workload-specific optimization. x86, ARM, and GPU-accelerated architectures coexist, with performance per watt, total cost of ownership, and software ecosystem maturity as key competitive focal points. Enterprise clients demand optimized solutions aligned with business needs and cost control. Vendors leverage strategic partnerships (e.g., Intel and NVIDIA) to offer full-stack solutions and secure long-term enterprise orders.

Differentiated Compute and Scenario-Specific Customization: The era of one-size-fits-all general-purpose chips is ending. The market increasingly demands deeply optimized solutions for specific application scenarios. Vendors who best understand and meet the unique requirements of end-use scenarios (e.g., industrial network protocols, automotive-grade certification, AI inference workloads) will capture market share.

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September 2025
Briocean

YOUR PREFERRED SUPPLIER FOR GLOBAL SOURCING

Briocean was established in 2008 as ISO14001, IS09001:2015, AS9120B and ANSI/ESDS20.20-2021 certified leading independent electronic component distributor, with our headquarters in Singapore. Our company specialises in insourcing and supply chain management servic es for the elec tronics manufacturing clients across a broad range of industries.

Our global network of over 10,000 vetted suppliers allows us to respond to the unique needs of our clients, from reducing component shortages to achieving significant cost savings. Our robust supplier management system and two state-of-the-art quality assurance centres in Shenzhen and Hong Kong ensure that we deliver reliable, traceable procurement services.

At Briocean, quality is our cornerstone. Our commitment is to ensure that every component we source is of the highest quality.